

SOLDERING

ECOREL™ FREE 305-21

SAC305 SOLDER PASTE
NO CLEAN SMT PRINTING & DISPENSING PROCESS
HIGH RELIABILITY APPLICATIONS

BENEFITS

ECOREL FREE 305-21 is especially designed for applications which needs high chemical reliability and where post reflow cleaning is not an option. This solder paste has excellent BONO test values, which is a key attribute to control the risk for electrochemical migration (ECM), especially when exposed to challenging conditions of high temperature and humidity.

The chemistry of this product is also available with other alloys or particle sizes on request.

PERFORMANCE	<ul style="list-style-type: none"> Very good wetting properties on all surface finishes, including OSP No graping, even on very small deposits Transparent colorless residue, even after multiple reflow cycles
COST	<ul style="list-style-type: none"> Minimizes line-down time & the need for re-work Good first pass yield testability in ICT
HSE	<ul style="list-style-type: none"> Lead Free No halogen Free of CMR containing substances

FEATURES

STANDARD OPTIONS

SPECIFICATIONS	ECOREL FREE 305-21	ECOREL FREE 305-21 T4	ECOREL FREE 305-21 T5
Alloy	Sn96,5Ag3Cu0,5	Sn96,5Ag3Cu0,5	Sn96,5Ag3Cu0,5
Melting point (°C/°F)	217/422	217/422	217/422
Metal content (%)	88.5 +/-0,5	88.5 +/-0,5	88 +/-0,5
Post reflow residues	Approximately 5% by w/w	Approximately 5% by w/w	Approximately 5% by w/w
Halogen content	No Halogen	No Halogen	No Halogen
Powder size	25-45 microns / Type 3	20-38 microns / Type 4	15-25 microns / Type 5
Spiral pump Viscosity (Pa.s 25°C) Malcom at a 10 rpm rotation speed	Typical 165	Typical 165	under evaluation
Viscosity (Pa.s 20°C) Brookfield RVT TF at 5 rpm	n.a.	n.a.	900-1100

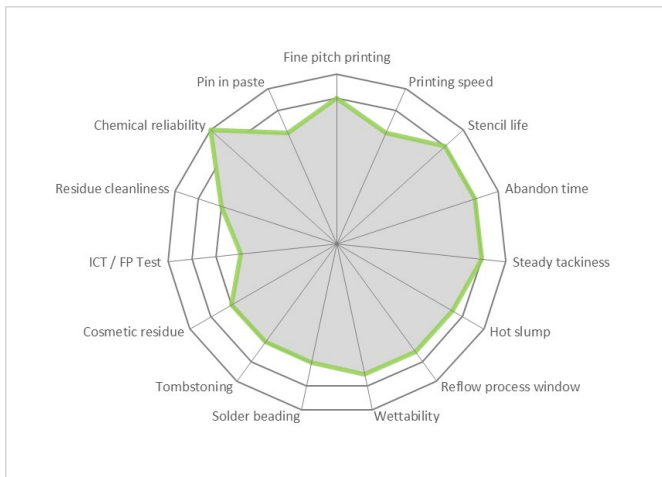
DISPENSING OPTIONS

SPECIFICATIONS	ECOREL FREE 305-21 T5-85
Alloy	Sn96,5Ag3Cu0,5
Melting point (°C/°F)	217/422
Metal content (%)	85
Post reflow residues	Approximately 5% by w/w
Halogen content	No Halogen
Powder size	15-25 microns / Type 5
Spiral pump Viscosity (Pa.s 25°C) Malcom at a 10 rpm rotation speed	under evaluation
Viscosity (Pa.s 20°C) Brookfield RVT TF at 5 rpm	550-750

CHARACTERISTICS

CHARACTERISTICS	VALUES	TEST METHOD
Flux Classification	ROLO	ANSI/J-STD-004B
	113	ISO 9454
Solder balling test	Pass	ANSI/J-STD-005
Copper mirror	Pass	ANSI/J-STD-004B
Copper corrosion	Pass	ANSI/J-STD-004B
SIR (IPC)	Pass	ANSI/J-STD-004B
SIR (Bellcore)	Pass	Bellcore
Electromigration (IPC / Bellcore)	Pass	ANSI/J-STD-004B / Bellcore
Bono Corrosion test (85°C / 85% HR - 15 days)	Pass Corrosion Factor <8%	Inventec procedure

RADAR CHART: ECOREL FREE 305-21 T4



PROCESS RECOMMENDATION

The best process will depend on factors such as operating conditions, equipment, board or component design. Our team is ready to advise you.

SOLDER PASTE PREPARATION

- Put the paste at room temperature for at least 4 hours prior to use.
- Before printing, it is essential to properly mix the solder paste, either manually with a spatula or by doing several preliminary prints on the stencil.
- Automatic solder paste mixing is neither required nor advised.

PRINTING GUIDELINE

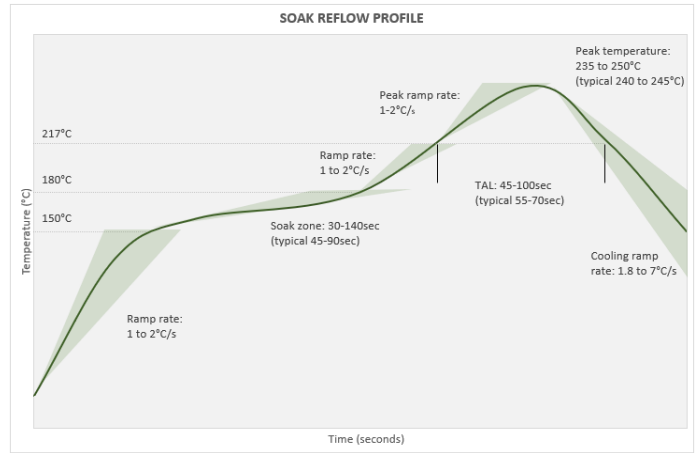
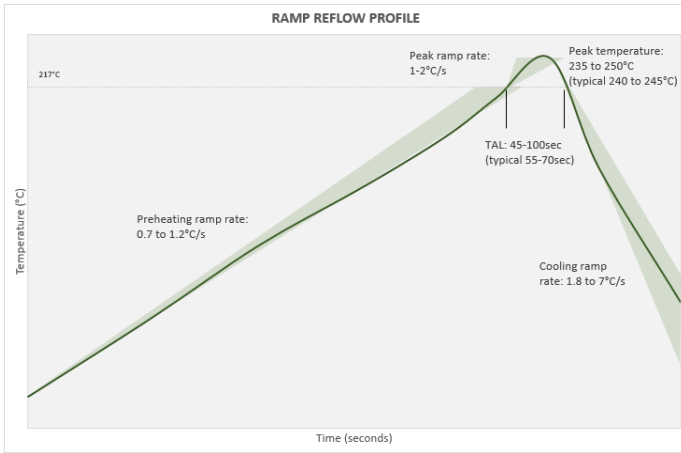
Apply the solder paste to the stencil to form a roll of 1 to 2 cm in diameter all along the squeegee or around 100g per 10 cm of squeegee length. This way, the solder paste will roll easily under the squeegees to offer excellent printing quality.

PARAMETER	REMARK
Printing speed	Minimum 20 to maximum 150 mm/s (1 to 6 inch/s) Maximum depends on printer capabilities
Minimum pitch	0.4 mm for Type 3 powder
Pressure	Guideline value for a 250 mm squeegee is 7 Kg at 100 mm/s Actual value depends on equipment, printing speed and squeegee length
Stencil life in continuous printing process	>12 hours
Abandon time between prints	>4 hours
Steady tackiness	>16 hours

REFLOW GUIDELINE

Although this paste performs very well under air, a nitrogen atmosphere will even more improve the wettability whereas achieving even a larger reflow process window.

Linear preheating ramp rate is recommended, however high-density boards may require a soak zone during preheating to stabilize the temperature over the circuit board before peak reflow.



REFLOW STEPS	REMARKS
Preheating ramp rate with linear preheating	0.7 to 1.2°C/s (according to the circuit board size and density)
Preheating steps in case of preheating soak zone	<ul style="list-style-type: none"> From 20 to 150°C (68 to 302°F) ramp rate 1 to 2°C/s Soak zone between 150 to 180°C (302 to 356°F): 60-140s reflow (typical soak 45-90s) From 170°C (380°F) to liquidus 1 to 2°C/s
Peak ramp rate	1 to 2 °C/s
Peak temperature	235 to 250°C (455 to 582°F) / 240 to 245°C (464 to 473°F) is optimum The paste can withstand a temperature higher than 250°C (482°F), but it is not recommended to preserve component integrity.
Time above liquidus	45 to 100s - 55 to 70s typical
Cooling ramp rate	1.8 to 7°C/s Studies has demonstrated 1.8 to 2.2 °C/s allows a more homogeneous joint structure and reduced surface crack formation.

CLEANING POST SOLDERING

This product is a no-clean solder paste, so cleaning is not required to meet IPC standards. The chemistry is specially designed so that any remaining flux residue is chemically inert and will not impact your assembled board or packaging under normal conditions. However, when cleaning is desired or required (e.g. high reliability assembly or to improved conformal coating adhesion), the flux residue can be easily removed with INVENTEC's own formulated flux cleaners.

Inventec has over 60 years' experience in high-tech cleaning for aqueous and solvent based systems. Our solder materials are aligned with our cleaning solutions, which guarantees excellent cleaning.

PROCESS TYPE	PCBA DEFLUXING SOLUTIONS
Manual	Quicksolv™ DEF90, Quicksolv™ DEF70, Promoclean™ TP61
Aqueous (Immersion or spray)	Promoclean™ DISPER 607, Promoclean™ DISPER 707, Promoclean™ DISPER 800
Co-solvent	Topklean™ EL 80 + Promosolv™ rinsing solvents
Mono-solvent (vapor phase)	Promosolv™ 70ES, Promosolv™ 70IS

PACKAGING, STORAGE & SHELF LIFE

- To ensure the best product performance, the recommended storage temperature range is from 0°C to 10°C.
- For an optimal preservation, store cartridges and syringes in a vertical position, tip downwards.
- Shelf-life is 12 months for jar packaging, 9 months for cartridges and 6 months for syringes.

AVAILABLE PACKAGING



JAR
250g & 500g



CARTRIDGE
600g & 1200g

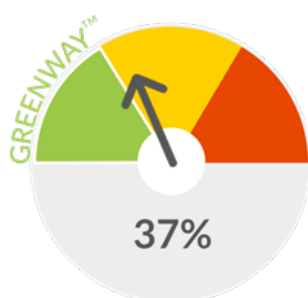


SYRINGE*
30g (10cc) & 100g (30cc)

*Syringes only available for dispensing options

HEALTH, SAFETY & ENVIRONMENT

ECOREL FREE 305-21 is **NOT** a **GREENWAY** product. Although fully in line with safety & environmental regulations, this product doesn't match our strict criteria to be labelled as a Greenway product. More info on our Greenway concept via this [link](#).



LOOKING FOR A MORE SUSTAINABLE SOLUTION?

GREENWAY ALTERNATIVE

- ECOREL 305-16LVD

In accordance with the Annex II of Directive 2011/65/UE (RoHS), including its amendments, we certify that this product does not contain quantities above 0.1% of Hg, Pb, Cr VI, PBB, PBDE, DEHP, BBP, DBP, DIBP and above 0.01% of Cd. INVENTEC PERFORMANCE CHEMICALS also fulfils its direct obligations under the REACH and Conflict Mineral regulations.

Please refer always to the Safety Data Sheet (SDS or MSDS) prior to use. Our SDS can be downloaded at www.quickfds.com. We will request to provide your email address, so we can automatically send you a new version of the SDS when a future update would occur.

TECHNICAL SUPPORT & FREE-OF-CHARGE TESTING

Inventec has a worldwide dedicated Technical Support team to help you along the various stages of our cooperation.

Depending on your request, we provide online or onsite support

- to select the right product based on your specific needs.
- to assist you in your product qualification process.
- to guide you with the initial set up of your process at all your worldwide manufacturing facilities.
- to provide fast response on technical issues which could occur at any time during mass production.

When flux cleaning is necessary, customers are welcome to visit our **CLEANING CENTERS** to witness the process firsthand and experience the effectiveness of our solutions. We offer both aqueous- and solvent-based processes.

Inventec is unique in the world by developing not only cleaning materials but also soldering and coating solutions. These materials are very closely linked with each other from a process point of view. Talking to our Technical Team, who understands very well these 3 different product groups, will help you greatly to overcome technical challenges within your overall process.

Contact our technical support via contact@inventec.dehon.com or your local sales representative.

ABOUT INVENTEC

Inventec is a global provider of SOLDERING, CLEANING, COATING, COOLING materials for Electronic, Semiconductor and Industrial applications. For over 60 years we have shown leadership in innovation by putting HEALTH IMPACT, SUSTAINABILITY and RELIABILITY at the core of our product development.

With ISO 9001 & 14001 production sites in France, Switzerland, USA, Mexico, Malaysia and China we can guarantee a smooth and cost-effective supply chain.

We supply to many industries but the excellent performance of our products in applications which demand high reliability, leads us to focus especially on the AUTOMOTIVE, AEROSPACE, SEMICONDUCTOR, ENERGY and MEDICAL industry.

www.inventec.dehon.com



SOLDERING
CLEANING
COATING
COOLING

This data is based on information that the manufacturer believes to be reliable and offered in good faith. In no event will INVENTEC PERFORMANCE CHEMICALS be responsible for special, incidental and consequential damages. The user is responsible to the Administrative Authorities (regulations for the protection of the Environment) for the conformity of his installation.

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